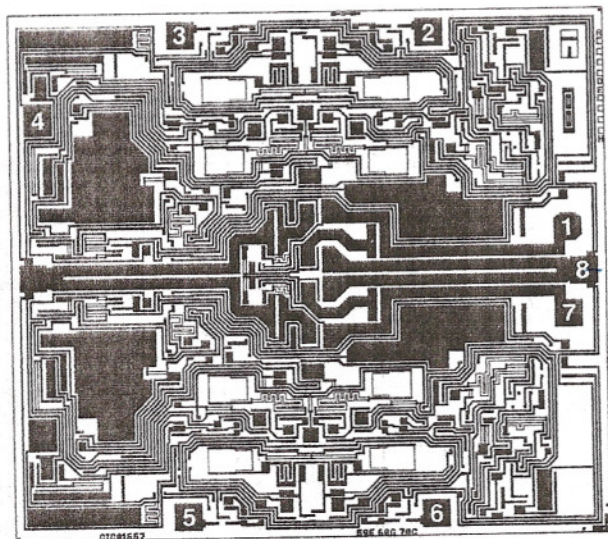




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



OPA1013 DIE TOPOGRAPHY

PAD	FUNCTION
1	Output A
2	-In A
3	+In A
4	V-
5	+In B
6	-In B
7	Output B
8	V+

Substrate Bias: $-V_s$

MECHANICAL INFORMATION

	MILS (0.001")	MILLIMETERS
Die Size	112 x 100 ±5	2.84 x 2.54 ±0.13
Die Thickness	20 ±3	0.51 ±0.08
Min. Pad Size	4 x 4	0.10 x 0.10
Backing	Gold	

See "DICE PRODUCTS" Section 17 in Data Book Supplement Volume 33c, or contact Burr-Brown for current information.

Top Material: Aluminum
Backside Material: Gold
Bond Pad Size: .004"
Backside Potential:
Mask Ref:

APPROVED BY: CD

DIE SIZE : .100"X .112"

DATE: 9/12/06

MFG: Burr Brown

THICKNESS: .012"

P/N:OPA1013